



Title of Change:	Conversion of 14L & 16L SOIC products to Extreme Density Lead Frame (XDLF) assembled at Amkor Technology Philippines P1.											
Proposed first ship date:	30 November 2017 <i>or earlier upon customer approval</i>											
Contact information:	Contact your local ON Semiconductor Sales Office or < Koen.Matthijs@onsemi.com >											
Samples:	Contact your local ON Semiconductor Sales Office											
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Phine.Guevarra@onsemi.com >.											
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and its conditions acceptable, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.											
Change Part Identification:	Affected products will be identified with date code											
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____											
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____											
Sites Affected:	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : _____ <input checked="" type="checkbox"/> External Foundry/Subcon site(s) Amkor Technology Philippines P1											
Description and Purpose:	<p>This Final Notification announces to customers that the Lead frame format of 14L & 16L SOIC products assembled in Amkor Technology, Philippines P1 is changed from HDLF (High density Lead frame) to XDLF (Extreme Density Lead Frame).</p> <p>Summarize on the table below are the packages for transfer and its equivalent bill of materials:</p> <table border="1" data-bbox="120 1339 1500 1493"> <thead> <tr> <th>Item of change</th> <th>Before</th> <th>After</th> </tr> </thead> <tbody> <tr> <td>Supplier</td> <td>PSMP</td> <td>MSHE</td> </tr> <tr> <td>Lead frame format(Length x width)</td> <td>HDLF(250X70MM)</td> <td>XDLF (300X100MM)</td> </tr> </tbody> </table>			Item of change	Before	After	Supplier	PSMP	MSHE	Lead frame format(Length x width)	HDLF(250X70MM)	XDLF (300X100MM)
Item of change	Before	After										
Supplier	PSMP	MSHE										
Lead frame format(Length x width)	HDLF(250X70MM)	XDLF (300X100MM)										



Reliability Data Summary:

The qualification is performed per type of package.

The principle of similarity will be applied: 1 qualification on 1 representative product will serve for all products qualified.

QV DEVICE NAME: AMIS41683CANN1G

PACKAGE : SOIC

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1000hrs	0/77
TC	JESD22-A104	Ta= -65°C to +150°C	500cyc	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL2 and 3 X IR at 260°C		0/462
SD	JSTD002	Ta = 245C, 10 sec		0/15

NOTE: AEC-1pager is attached.

To access file attachments on pdf copy of PCN, please be guided by the steps below:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
4. Then click on the attached file/s

Electrical Characteristic Summary :

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
AMIS41683CANN1RG	AMIS41683CANN1G
NCV7420D23R2G	